Product Change Notification

104263 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 104263 - 00

Change Title: Intel(r)TXN174210850,TXN172010850 and TXN172090850, PCN 104263-00, FYI, Assembly Site Change to Malaysia.

Date of Publication: July 28, 2004

Type of Change Notification:

FYI - (For Your Information)

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 28, 2004

Description of Change to the Customer:

Intel® TXN174210850, TXN172010850 and TXN172090850 10GBASE-SR XENPAK and XPAK optical transceiver will be assembled at a 2nd factory in Malaysia starting October 2004. Customers can distinguish these units by referring to the product serial numbers and country of origin. Current product made in the USA has serial numbers starting with "USC" and country of origin showing "Made in USA", whereas product assembled from our 2nd factory in Malaysia will have serial numbers starting with "MYC" and with words "Made in Malaysia".

Assembly and test processes in the 2nd factory are equivalent to current US factory. There are no design changes as a result of this assembly site transfer.

Customers should expect product assembled, tested and delivered from the 2nd factory in Malaysia

Customer Impact of Change and Recommended Action:

No customer action is required. Product manufactured from the 2nd factory is the same as current product being shipped with the exception of serial number and country of origin marking.

Products Affected / Intel Ordering Codes:

System Products Table

Affected Product Code	Pre-Change MM#
TXN172010850G27	860002
TXN172010850G37	859741
TXN172010850G3A	860126
TXN172090850G27	860003
TXN172090850G37	859742
TXN174210850F06	858336
TXN174210850F0A	859999
TXN174210850F0C	860001
TXN174210850F16	859743
TXN174210850F1A	859744
TXN174210850F1C	859746

Reference Documents / Attachments:

Document:	**Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
July 28, 2004	00	Originally Published PCN